

Attorney's Docket No.: 10559-857001/P17305

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JUN 10 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Sarah E. Kim et al. Art Unit: 2814
Serial No.: 10/659,044 Examiner: Thao X Le
Filed : September 9, 2003 Assignee: Intel Corporation
Title : THICK METAL LAYER INTEGRATED PROCESS FLOW TO IMPROVE
POWER DELIVERY AND MECHANICAL BUFFERING

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

*Please
Enter.*
In response to the Office action mailed April 11, 2005,
please amend the application as follows:

*TL
07/21/05*
Amendments to the Claims begin on page 2 of this paper.

Remarks/Arguments begin on page 9 of this paper.

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